Sumter Sales AND MARKETING

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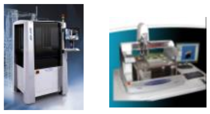
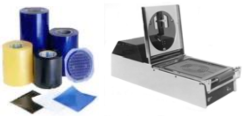
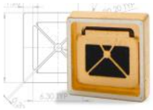
ADT Dicing Advanced Dicing Technologies **Dicing for Wafers, Hard Materials, and Package Singulation**		➢ Dicing Saws ➢ Saw Blades (Hub and Hubless) ➢ Peripheral Equipment ➢ Dicing Accessories
STAr **Wafer and Package Level Test Equipment / Probe Cards**		➢ Probe Cards (Cantilever and Vertical) for Parametric, Reliability, and Functional Test ➢ Reliability Testers; TDDB, HCI, EM, etc ➢ Functional Test System; linear, power, & mixed signal markets ➢ High Voltage, Current, Power Test Solutions ➢ Probe Station
AIR-VAC **Multi-Functional Precision Assembly Systems**		➢ Robotic platform for Product Micro Assembly operations ➢ Flexible design configured based on application requirements ➢ Options include Multi-input, Bonding, Dispensing, Vision, Marking, Force-Controlled Placement, Test, Sort, and more
PPI **Laser Trim & Laser Drilling Systems**		➢ Laser Trim - Thick or thin film resistor trim to improve precision/performance. 4 independent flying probes eliminate need for probe cards and increase system flexibility ➢ High throughput Laser Drilling and routing of complex features in flex and ridged HDI PCB's. Available in dual laser (UV + CO2), UV, and CO2 Models
FTS Systems SP SCIENTIFIC Making Time for Science **Temperature Cycling Systems**		➢ Widest Temperature Range; from -80° to +350°C ➢ Fastest Temperature Transition Rate ➢ Smallest Industry Footprint
ROYCE Instruments **Die Sorting and Bond Test Equipment**		➢ Automatic and Semi-Automatic Die Handling and Sorting Systems. Vision Inspection Options ➢ Pull and Shear Testers for Wire Bond, Die Bond, BGA Ball, etc
Semiconductor Equipment Corp. **Wafer and Die Processing Tools and Materials**		➢ Wafer Dicing Tapes - Pressure Sensitive, UV, Heat Release ➢ Film Frame Mounters for Dicing, Backgrind, etc. (Manual, Semi-Auto and Automatic) ➢ Die Bonders ➢ UV Exposure System ➢ P&P Systems, Die Ejectors, Wafer Die Matrix Expander, etc ➢ FOUP and Cassette Cleaning
HAST SOLUTIONS **HAST Boards and Test Racks**		➢ HAST Boards for all package types and board size formats ➢ Universal, Pin Programmable, and Dedicated Configurations ➢ Burn-in and THB Boards also available ➢ HAST Chamber Test Racks and other fixturing also available
SURON Precision Technology **Packaging Materials**		➢ Lids; standard with preform, absorber material, windows, etc ➢ Modules ➢ EMI/RFI Shielding ➢ Solder Preforms; Pre-cut to desired size and shape ➢ Lead Frames; glass-to-metal sealing, package, capacitor, etc
MP Micro Point Pro **Wire Bonding and Specialty Tools**		➢ Wedge Tools and Capillaries for Wire Bonding ➢ Die Bonding; Die Collets, Vacuum Pick Up Tools, Ejector pins ➢ Dispensing Nozzles / Tools

January 2021